



Pages 1 to 13

TRANSISTORS, SWITCHING, PNP

BASED ON TYPE 2N3467

ESCC Detail Specification No. 5208/009

as applicable

Issue 3 - Draft A	October 2008
-------------------	-------------------------



Document Custodian: European Space Agency - see <https://escies.org>



as applicable

LEGAL DISCLAIMER AND COPYRIGHT

European Space Agency, Copyright © 2008. All rights reserved.

The European Space Agency disclaims any liability or responsibility, to any person or entity, with respect to any loss or damage caused, or alleged to be caused, directly or indirectly by the use and application of this ESCC publication.

This publication, without the prior permission of the European Space Agency and provided that it is not used for a commercial purpose, may be:

- copied in whole, in any medium, without alteration or modification.
- copied in part, in any medium, provided that the ESCC document identification, comprising the ESCC symbol, document number and document issue, is removed.



DOCUMENTATION CHANGE NOTICE

(Refer to <https://escies.org> for ESCC DCR content)

DCR No.	CHANGE DESCRIPTION
● 388	Specification up issued to incorporate editorial and technical changes per DCR.

t6d

At $T_{case} \leq +25^{\circ}C$

Characteristics	Symbols	Maximum Ratings	Unit	Remarks
Collector-Base Voltage	V_{CB0}	-40	V	Over entire operating temperature range
Collector-Emitter Voltage	V_{CEO}	-40	V	
Emitter-Base Voltage	V_{EB0}	-5	V	
Collector Current	I_C	-1	A	Continuous
Power Dissipation	P_{tot1}	1	W	At $T_{amb} \leq +25^{\circ}C$
	P_{tot2}	5	W	Note 1
Operating Temperature Range	T_{op}	-65 to +200	$^{\circ}C$	Note 1
Storage Temperature Range	T_{stg}	-65 to +200	$^{\circ}C$	Note 1
Soldering Temperature	T_{sol}	+265	$^{\circ}C$	Note 2

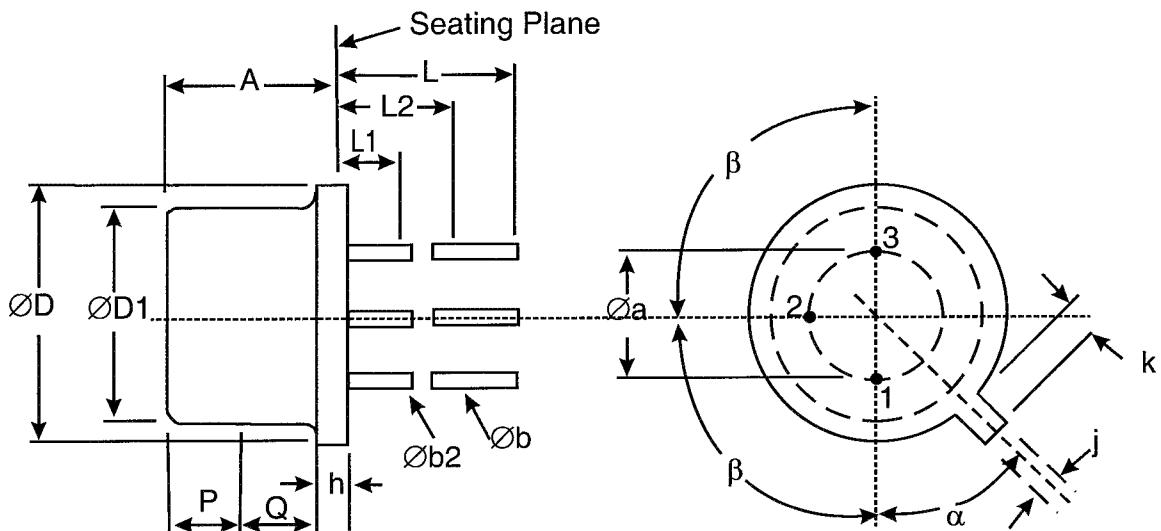
see attached

NOTES:

- For $T_{amb} > +25^{\circ}C$, derate linearly to 0W at $+200^{\circ}C$
- For Variants with tin-lead plating or hot solder dip lead finish all testing performed at $T_{amb} > +125^{\circ}C$ shall be carried out in a 100% inert atmosphere.
- Duration 10 seconds maximum at a distance of not less than 1.5mm from the device body and the same lead shall not be resoldered until 3 minutes have elapsed.

1.6 PHYSICAL DIMENSIONS AND TERMINAL IDENTIFICATION

1.6.1 Metal Can Package (TO-39) - 3 lead



Symbols	Dimensions mm		Notes
	Min	Max	
Øa	4.83	5.35	
A	6	6.6	
Øb	0.4	0.533	2, 3
Øb2	0.4	0.483	2, 3

Thermal Resistance, Junction-to-Ambient	$R_{th(j-a)}$	175	°C/W	
Thermal Resistance, Junction-to-Case	$R_{th(j-c)}$	30	°C/W	